Method Of Mounting And Demounting A Semiconductor Wafer And Substance Mixture Suitable For Carrying Out The Method

Abstract

The invention relates to a method of mounting and demounting a semiconductor wafer, in which a temperature-dependently adhering and curing joint is provided by a substance mixture between the semiconductor wafer and a carrier plate and the substance mixture contains a colophonium resin which is chemically modified and esterified, and the cured joint is released again after polishing the semiconductor wafer. The method is one wherein the cured joint is released with water. The invention also relates to a substance mixture suitable for carrying out the method.